

## LIST OF CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Currently amended) A chemical mechanical planarization (CMP) system, the system comprising:

a polishing surface;

a platen disposed along an underside of the polishing surface; and

a retaining ring surrounding the platen, the retaining ring including a fixed lower annular sleeve.

2. (Currently amended) The CMP system of claim 1, wherein the retaining ring includes ~~a lower annular sleeve and~~ an upper annular sleeve moveably disposed over the lower annular sleeve.

3. (Original) The CMP system of claim 1, wherein the polishing surface is a belt.

4. (Original) The CMP system of claim 2, wherein the lower annular sleeve includes at least two lower curved members and the upper annular sleeve includes at least two upper curved members, each of the at least two upper curved members being moveably disposed over a corresponding lower curved member.

5. (Original) The CMP system of claim 2, wherein the lower annular sleeve includes a base having an inner sidewall and an outer sidewall extending

therefrom and the upper annular sleeve includes a top having an inner sidewall and an outer sidewall extending therefrom.

6. (Original) The CMP system of claim 5, wherein an interior surface of each of the inner and outer sidewalls of the upper annular sleeve includes a protrusion, and an exterior surface of each of the inner and outer sidewalls of the lower annular sleeve includes a protrusion.

7. (Original) The CMP system of claim 6, wherein the protrusions of the upper and lower annular sleeves are positioned such that when the protrusion of the upper annular sleeve abuts against the protrusion of the lower annular sleeve, the top of the upper annular sleeve aligns to the underside of the polishing surface without disturbing an interaction angle between a wafer and the polishing surface.

8. (Currently amended) The CMP system of claim 1, wherein a top surface of ~~the~~ an upper annular sleeve has a channel formed therein.

9. (Currently amended) The CMP system of claim 1, wherein a top surface of ~~the~~ an upper annular sleeve of the retaining ring has at least one hole defined therein.

Claims 11-16 Cancelled